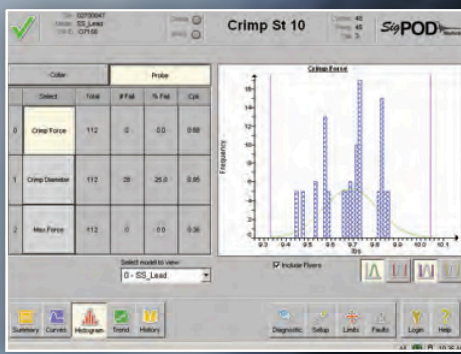


sigPOD offers a range of feature checks for crimp analysis, allowing device manufacturers to increase efficiency, drastically lower scrap rates, and maintain robust historical test data.



Minimizing waste and increasing crimp test processes efficiency are major challenges in manufacturing. Improperly crimped sub-components and batch testing practices cause high scrap rates. Additionally, inadequate testing practices increase waste; some parts will fail visual or other tests, but further tests show that the crimp was in fact satisfactory.

The Sciometric sigPOD Crimp application offers a wide range of feature checks for crimp analysis. This includes 100% monitoring of crimp or staking operations, where up to 4 crimps can be simultaneously tested. Real time pass fail indication provides immediate feedback while full serialized traceability including test waveforms and other historical data are available in production.

Using the sigPOD crimp application, costly downstream waste is eliminated as defects are detected at the source of the operation. Efficiency is drastically increased with lean in process testing, where up to 4 crimps can be simultaneously monitored. Once in production, the sigPOD platform, in conjunction with QualityWorX data analytics software, acts as a process examiner to ensure continued quality assurance and traceability.

Benefits

- 100% monitoring of crimp or staking operation
- Defects detected upstream
- Sequential or simultaneous monitoring of up to 4 crimps
- Signature analysis and full reporting
- Full serialized traceability including test waveforms
- Real time pass fail indication
- Integral SPC analysis for multiple feature checks